

## Technical Information

# 6493 Platinum/Palladium/Silver Conductor

The platinum/palladium/silver conductor composition 6493 was developed for applications with very demanding solder leach resistance requirements. Its high platinum and palladium contents also inhibit silver migration. It does not contain cadmium, lead, or highly toxic organic solvents. Key features include:

- Excellent Solder Acceptance and Leach Resistance
- Good Line Resolution
- High Adhesion
- Compatibility with Dielectrics and Resistors.

### TYPICAL FIRED FILM CHARACTERISTICS<sup>(1)</sup>

<b>Fired Thickness</b>	14-17 $\mu\text{m}$
<b>Line Resolution</b>	175/125 $\mu\text{m}$ line/space using 150/150 $\mu\text{m}$ pattern and 325 mesh screen
<b>Resistivity</b>	40-50 milliohms / sq at 16 $\mu\text{m}$ fired thickness
<b>Solder Acceptance<sup>(2)</sup></b> 36/62/2 Sn/Pb/Ag, on 96% alumina	Excellent
<b>Solder Leach Resistance<sup>(3)</sup></b>	12-16 Cycles
<b>Adhesion<sup>(4)</sup></b>	
Initial	18 - 30 N
48 Hours @ 150° C	16 - 28 N

(1) Typical properties are based on testing of several batches under various processing conditions. They are not intended as specification limits.

(2) Excellent refers to nearly 100% coverage of both pads and lines, after a 5-second dip in the solder bath at 225 +/-5°C, using Alpha 611 mildly activated flux.

(3) Cycles consist of 10-second dips in a 225 +/-5°C solder bath. Each cycle is preceded by dipping in Alpha 611 flux.

(4) The adhesion test consists of attaching 20 AWG tinned copper wire to .080"x.080" pads, by dipping in 225 +/-5°C solder for 5 seconds. The wires are then bent 90 degrees and pulled, while a force gauge records the peel strength.

## COMPOSITION PROPERTIES

**Viscosity:**  $150 \pm 30$  Kcps, when measured with Brookfield HBT, Spindle #14, utility cup, 10 RPM, 25° &

**Specific Gravity:** 3.4 - 3.8 g/cm<sup>3</sup>

**Recommended Thinner:** KOARTAN A-1039

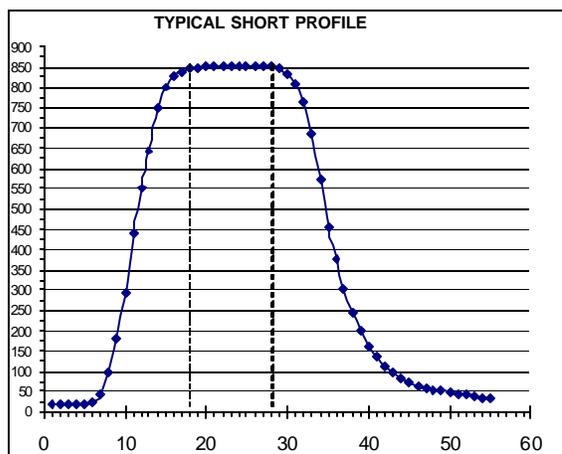
## RECOMMENDED PROCESSING PROCEDURE

**Printing:** Printing with 325 mesh stainless steel screen using 10-15  $\mu\text{m}$  emulsion and 45 degree angle is recommended. Other mesh counts, 200-250, and emulsion thicknesses, 5-25  $\mu\text{m}$ , may be used for special applications. Squeegee speeds of up to 10 inches/sec may be utilized.

Coverage is approximately 80 cm<sup>2</sup>, when utilizing 325 mesh screen and a wet print thickness of about 35  $\mu\text{m}$ .

**Drying:** Wet prints should be allowed to level for 5-10 minutes prior to drying. Dry for 10-15 minutes in a convection oven or belt dryer at 125°C-150°C.

**Firing:** Firing in air using a belt furnace and a 36-60 minute profile, with 10 minutes at a peak temperature of 850°C is recommended. Air flow rates must be optimized to ensure that the products of binder burn-off discharge properly and create a fully oxidizing atmosphere in the muffle.



**Storage and Shelf Life:** Store in tightly capped containers at room temperature. Shelf life is 6 months for unopened jars. Under ordinary conditions of storage and use the product should not require thinning. However, solvent loss during extended printing runs may be corrected by incorporating up to 0.5% of Koartan A-1039 thinner.

The information presented herein is based on data believed to be dependable and is accurate and reliable to the best of our knowledge and belief, but not guaranteed to be so. Koartan Company assumes no liability arising from the use of this product or the information provided herein. Nothing herein is to be construed as recommending any practice or any product in violation of any patent or in violation of any law or regulation.